SiRA84BDP

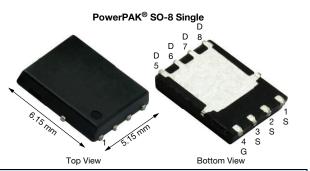
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Vishay Siliconix

RoHS COMPLIANT

HALOGEN

FREE



PRODUCT SUMMARY 30 V_{DS} (V) $R_{DS(on)}$ max. (Ω) at $V_{GS} = 10$ V 0.0046 $R_{DS(on)}$ max. ($\Omega)$ at V_{GS} = 4.5 V 0.0071 Q_a typ. (nC) 10.6 70 I_D (A) ^a Configuration Single

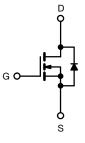
FEATURES

N-Channel 30 V (D-S) MOSFET

- TrenchFET[®] Gen IV power MOSFET
- 100 % R_g and UIS tested
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

APPLICATIONS

- High power density DC/DC
- Synchronous rectification
- VRMs and embedded DC/DC



N-Channel MOSFET

ORDERING INFORMATION	
Package	PowerPAK SO-8
Lead (Pb)-free and halogen-free	SiRA84BDP-T1-GE3

ABSOLUTE MAXIMUM RATINGS	(T _A = 25 °C, unless	s otherwise no [.]	ted)		
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-source voltage		V _{DS}	30	v	
Gate-source voltage		V _{GS}	+20, -16		
	T _C = 25 °C		70		
Continuous drain surrant (T 150 °C)	T _C = 70 °C		56		
Continuous drain current (T _J = 150 °C)	T _A = 25 °C	I _D	22 ^{b, c}		
	T _A = 70 °C		18 ^{b, c}	А	
Pulsed drain current (t = 100 µs)		I _{DM}	150	A	
Continuous source-drain diode current	T _C = 25 °C		33		
Continuous source-drain diode current	T _A = 25 °C	I _S	3.3 ^{b, c}		
Single pulse avalanche current	L = 0.1 mH	I _{AS}	15		
Single pulse avalanche energy		E _{AS}	11.3	mJ	
	T _C = 25 °C		36		
Movimum power dissinction	T _C = 70 °C		23	W	
Maximum power dissipation	T _A = 25 °C	P _D	3.7 ^{b, c}	vv	
	T _A = 70 °C		2.4 ^{b, c}		
Operating junction and storage temperature rar	nge	T _J , T _{stg}	-55 to +150	°C	
Soldering recommendations (peak temperature) ^{d, e}		-	260		

THERMAL RESISTANCE RATINGS					
PARAMETER		SMYBOL	TYPICAL	MAXIMUM	UNIT
Maximum junction-to-ambient ^{b, f}	t ≤ 10 s	R _{thJA}	28	34	°C/W
Maximum junction-to-case (drain)	Steady state	R _{thJC}	2.7	3.5	0/11

Notes a. Based on T_C = 25 $^\circ C$

b. Surface mounted on 1" x 1" FR4 board

t = 10 s c.

See solder profile (<u>www.vishay.com/doc?73257</u>). The PowerPAK SO-8 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection d.

Rework conditions: manual soldering with a soldering iron is not recommended for leadless components Maximum under steady state conditions is 72 °C/W e.

f.

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SiRA84BDP

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PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static	1 1		1		1		
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 V, I_D = 250 \mu A$	30	-	-		
Drain-source breakdown voltage ^(c) (transient)	V _{DSt}	$\label{eq:VGS} \begin{array}{l} V_{GS} = 0 \ V, \ I_{D(aval)} = 40 \ A, \\ t_{transcient} \leq 50 \ ns \end{array}$	36	-	-	V	
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	L 050 A	-	15.2	-		
V _{GS(th)} temperature coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA	-	-4.8	-	mv/°C	
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	1.2	-	2.4	V	
Gate-source leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = +20, -16 V	-	-	± 100	nA	
7		$V_{DS} = 30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$	-	-	1		
Zero gate voltage drain current	I _{DSS}	$V_{DS} = 30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 55 ^{\circ}\text{C}$	-	-	10	μA	
On-state drain current ^a	I _{D(on)}	$V_{DS} \ge 5 V$, $V_{GS} = 10 V$	30	-	-	Α	
		V _{GS} = 10 V, I _D = 15 A	-	0.0033	0.0046	0	
Drain-source on-state resistance ^a	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 10 \text{ A}$	-	0.0052	0.0071	Ω	
Forward transconductance ^a	g fs	$V_{DS} = 15 \text{ V}, \text{ I}_{D} = 25 \text{ A}$	-	55	-	S	
Dynamic ^b			1		1		
Input capacitance	C _{iss}		-	1050	-		
Output capacitance	C _{oss}		-	390	-	V mV/° V nA μA A Ω S PF nC Ω nC	pF
Reverse transfer capacitance	C _{rss}	V_{DS} = 15 V, V_{GS} = 0 V, f = 1 MHz	80	-			
C _{rss} /C _{iss} ratio			-	0.08	0.16		
		$V_{DS} = 15 \text{ V}, \text{ V}_{GS} = 10 \text{ V}, \text{ I}_{D} = 10 \text{ A}$	-	20.7	32		
Total gate charge	Qg		-	10.6	16		
Gate-source charge	Q _{gs}	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 10 \text{ A}$	-	3.6	-	nC	
Gate-drain charge	Q _{gd}		-	4.5	-		
Output charge	Q _{oss}	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}$	-	10	-		
Gate resistance	Rg	f = 1 MHz	0.3	1.4	2.8	Ω	
Turn-on delay time	t _{d(on)}		-	10	20		
Rise time	t _r	$V_{DD} = 15 \text{ V}, \text{ R}_{\text{L}} = 1.5 \Omega$	-	5	10		
Turn-off delay time	t _{d(off)}	$I_D \cong 10 \text{ A}, V_{\text{GEN}} = 10 \text{ V}, R_g = 1 \Omega$	-	20	40	-	
Fall time	t _f		-	5	10		
Turn-on delay time	t _{d(on)}		-	20	40	ns	
Rise time	t _r	$V_{DD} = 15 \text{ V}, \text{ R}_{L} = 1.5 \Omega$	-	70	140		
Turn-off delay time	t _{d(off)}	$I_D \cong 10 \text{ A}, V_{\text{GEN}} = 4.5 \text{ V}, R_g = 1 \Omega$	-	20	40		
Fall time	t _f	-	-	15	30		
Drain-Source Body Diode Characteristic	· · ·		1		1		
Continuous source-drain diode current	Is	T _C = 25 °C	-	-	33		
Pulse diode forward current ^a	I _{SM}	<u> </u>	-	-	150	A	
Body diode voltage	V _{SD}	I _S = 10 A	-	0.8	1.1	V	
Body diode reverse recovery time	t _{rr}	0	-	20	40	ns	
Body diode reverse recovery charge	Q _{rr}	I _F = 10 A, di/dt = 100 A/µs,	_	6	15	nC	
Reverse recovery fall time	t _a	$T_J = 25 \text{ °C}$	-	9	-		
Reverse recovery rise time	t _b	-	_	11	-	ns	

Notes

a. Pulse test: pulse width $\leq 300~\mu\text{s},\,duty~cycle \leq 2~\%$

b. Guaranteed by design, not subject to production testing

c. Based on characterization, not subject to production testing

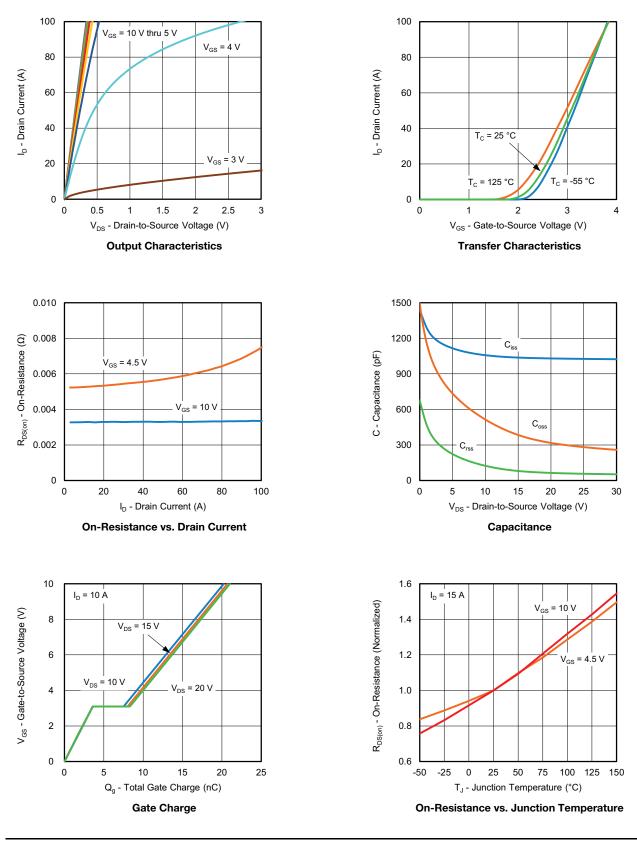
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

2



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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



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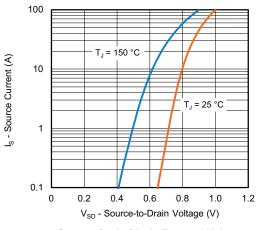
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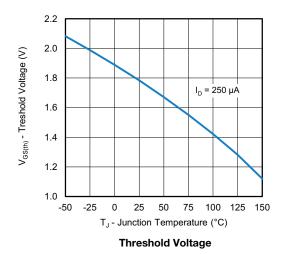


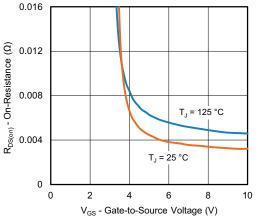
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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

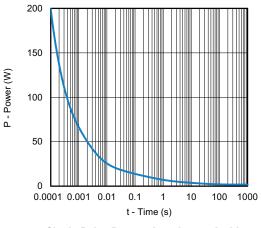


Source-Drain Diode Forward Voltage

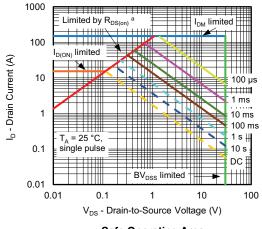




On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Ambient



Safe Operating Area

4

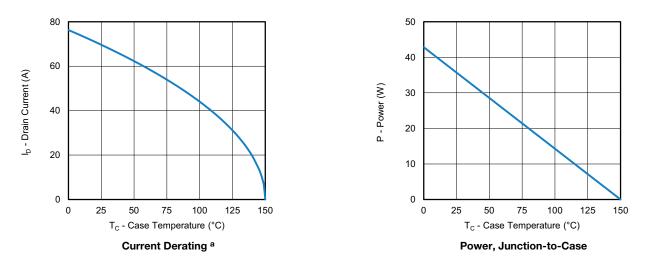
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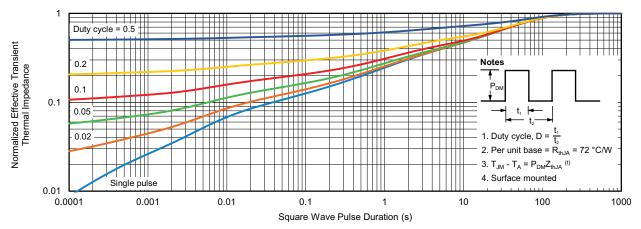
Note

a. The power dissipation P_D is based on T_J max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit

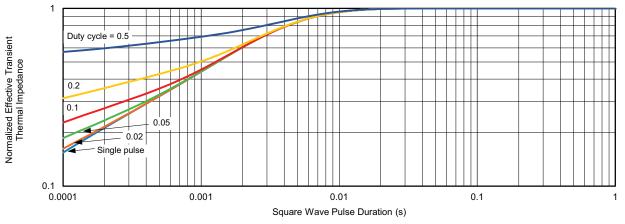


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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package / tape drawings, part marking, and reliability data, see www.vishay.com/ppg?77068.

D2

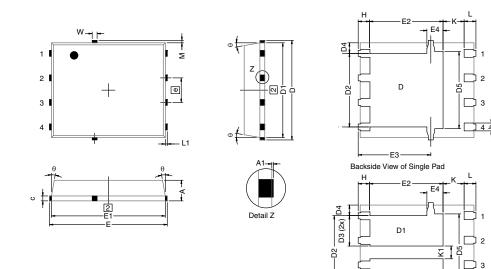
E3

Backside View of Dual Pad



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PowerPAK[®] SO-8, (Single/Dual)



Notes

1. Inch will govern.

2 Dimensions exclusive of mold gate burrs.

3. Dimensions exclusive of mold flash and cutting burrs.

DIM		MILLIMETERS			INCHES			
DIM.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX		
А	0.97	1.04	1.12	0.038	0.041	0.044		
A1		-	0.05	0	-	0.002		
b	0.33	0.41	0.51	0.013	0.016	0.020		
С	0.23	0.28	0.33	0.009	0.011	0.013		
D	5.05	5.15	5.26	0.199	0.203	0.207		
D1	4.80	4.90	5.00	0.189	0.193	0.197		
D2	3.56	3.76	3.91	0.140	0.148	0.154		
D3	1.32	1.50	1.68	0.052	0.059	0.066		
D4		0.57 typ.			0.0225 typ.			
D5		3.98 typ.			0.157 typ.			
E	6.05	6.15	6.25	0.238	0.242	0.246		
E1	5.79	5.89	5.99	0.228	0.232	0.236		
E2	3.48	3.66	3.84	0.137	0.144	0.15 ⁻		
E3	3.68	3.78	3.91	0.145	0.149	0.154		
E4		0.75 typ.		0.030 typ.				
е		1.27 BSC			0.050 BSC			
К		1.27 typ.		0.050 BSC 0.050 typ.				
K1	0.56	-	-	0.022	-	-		
Н	0.51	0.61	0.71	0.020	0.024	0.028		
L	0.51	0.61	0.71	0.020	0.024	0.028		
L1	0.06	0.13	0.20	0.002	0.005	0.008		
θ	0°	-	12°	0°	-	12°		
W	0.15	0.25	0.36	0.006	0.010	0.014		
М		0.125 typ.			0.005 typ.			

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Application Note 826

Vishay Siliconix

RECOMMENDED MINIMUM PADS FOR PowerPAK® SO-8 Single



Recommended Minimum Pads Dimensions in Inches/(mm)

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